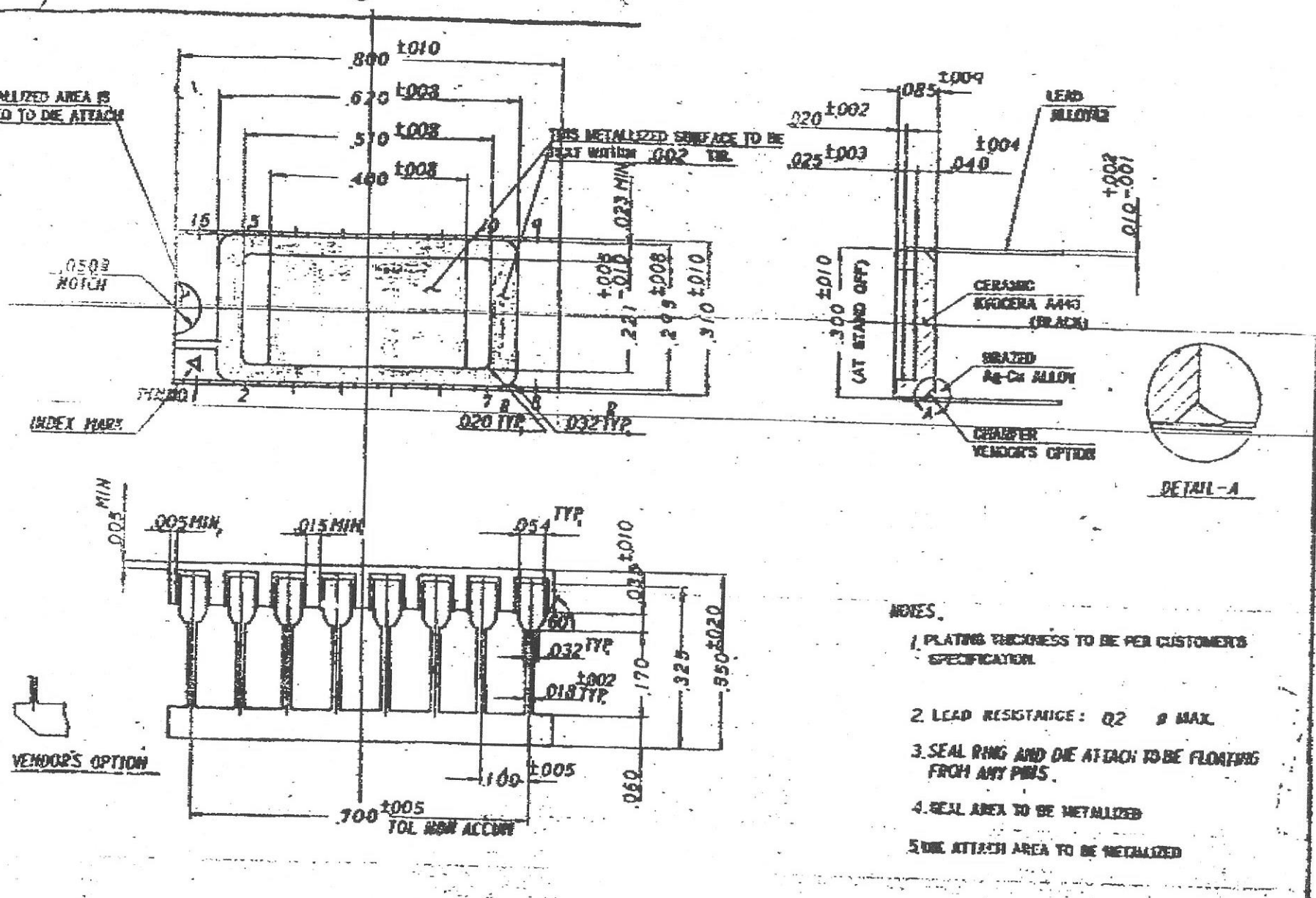


THIS METALLIZED AREA IS CONNECTED TO DIE ATTACH PAD

THIS METALLIZED SURFACE TO BE TEST WITHIN .002 TYP.



- NOTES.
1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
  2. LEAD RESISTANCE: 0.2 Ω MAX.
  3. SEAL RING AND DIE ATTACH TO BE FLOATING FROM ANY PINS.
  4. SEAL AREA TO BE METALLIZED
  5. DIE ATTACH AREA TO BE METALLIZED

				NAME	16 LEAD SIZE BRAZED PACKAGE		TOLERANCES	SDMS-518-1 B-0	
				SCALE	5:1		MATERIAL		APPROVED
						AS SHOWN		DATE	
								MAY 9 1984	
CHANGE	DATE	DRAWN	CHECKED	KYOCERA CORPORATION		KYOTO JAPAN		DRAWING NO. KD-84516 1/2	

